



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP80N06S2-09	Issued	04. May 2021
MA#	MA001047456		
Package	PG-TO220-3-1	Weight*	2038.15 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.888	0.29	0.29	2889	2889
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.01	40.06	400036	400557
wire	non noble metal	aluminium	7429-90-5	7.149	0.35	0.35	3507	3507
encapsulation	inorganic material	zinc oxide	1314-13-2	5.925	0.29		2907	
	miscellaneous	miscellaneous	-	23.700	1.16		11628	
	plastics	epoxy resin	-	88.874	4.36		43605	
	inorganic material	silicon dioxide	60676-86-0	473.994	23.26	29.07	232561	290701
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10530	10530
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.086			42	
	noble metal	silver	7440-22-4	0.107	0.01		53	
	non noble metal	lead	7439-92-1	4.089	0.20	0.21	2006	2101
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.92	28.96	289217	289594
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com